



Hard disk for XP700

Part no.
Article no.

OS-HDU-A4-S
140375

Technical data

Power supply

| | | | |
|--------------------------|--|--|--------------|
| Note on heat dissipation | | | not relevant |
|--------------------------|--|--|--------------|

Environmental conditions

| | | | |
|------------------------------------|--|----|------|
| Temperature | | | |
| Operating ambient temperature min. | | °C | 0 |
| Operating ambient temperature max. | | °C | + 50 |

Design verification as per IEC/EN 61439

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|--|--|----|--|
| Technical data for design verification | | | |
| Operating ambient temperature min. | | °C | 0 |
| Operating ambient temperature max. | | °C | 50 |
| IEC/EN 61439 design verification | | | |
| 10.2 Strength of materials and parts | | | |
| 10.2.2 Corrosion resistance | | | Meets the product standard's requirements. |
| 10.2.3.1 Verification of thermal stability of enclosures | | | Meets the product standard's requirements. |
| 10.2.3.2 Verification of resistance of insulating materials to normal heat | | | Meets the product standard's requirements. |
| 10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects | | | Meets the product standard's requirements. |
| 10.2.4 Resistance to ultra-violet (UV) radiation | | | Meets the product standard's requirements. |
| 10.2.5 Lifting | | | Does not apply, since the entire switchgear needs to be evaluated. |
| 10.2.6 Mechanical impact | | | Does not apply, since the entire switchgear needs to be evaluated. |
| 10.2.7 Inscriptions | | | Meets the product standard's requirements. |
| 10.3 Degree of protection of ASSEMBLIES | | | Meets the product standard's requirements. |
| 10.4 Clearances and creepage distances | | | Meets the product standard's requirements. |
| 10.5 Protection against electric shock | | | Does not apply, since the entire switchgear needs to be evaluated. |
| 10.6 Incorporation of switching devices and components | | | Does not apply, since the entire switchgear needs to be evaluated. |
| 10.7 Internal electrical circuits and connections | | | Is the panel builder's responsibility. |
| 10.8 Connections for external conductors | | | Is the panel builder's responsibility. |
| 10.9 Insulation properties | | | |
| 10.9.2 Power-frequency electric strength | | | Is the panel builder's responsibility. |
| 10.9.3 Impulse withstand voltage | | | Is the panel builder's responsibility. |
| 10.9.4 Testing of enclosures made of insulating material | | | Is the panel builder's responsibility. |
| 10.10 Temperature rise | | | The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices. |
| 10.11 Short-circuit rating | | | Is the panel builder's responsibility. |
| 10.12 Electromagnetic compatibility | | | Is the panel builder's responsibility. |
| 10.13 Mechanical function | | | The device meets the requirements, provided the information in the instruction leaflet (IL) is observed. |

Technical data ETIM 6.0

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| PLC's (EG000024) / PLC memory card (EC000192) | | | |
| Electric engineering, automation, process control engineering / Control / Programmable logic control (SPS) / SPS memory unit (ecl@ss8.1-27-24-22-12 [AKE535011]) | | | |
| Type of memory | | | - |
| Memory size | | kByte | 40000000 |